

HIGH-SPEED 3.3V 32/16K x 16 SYNCHRONOUS DUAL-PORT STATIC RAM

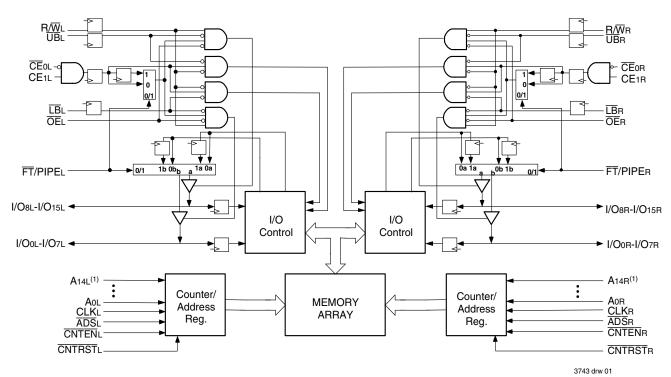
70V9279/69S/L

Features:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
 - Commercial: 7.5/9ns (max.)
 - Industrial: 7.5ns (max.)
- Low-power operation
 - IDT70V9279/69L
 Active: 429mW (typ.)
 Standby: 1.32mW (typ.)
- ◆ Flow-through or Pipelined output mode on either port via the FT/PIPE pin
- Counter enable and reset features
- Dual chip enables allow for depth expansion without additional logic

- Full synchronous operation on both ports
 - 4ns setup to clock and 1ns hold on all control, data, and address inputs
 - Data input, address, and control registers
 - Fast 6.5ns clock to data out in the Pipelined output mode
 - Self-timed write allows fast cycle time
 - 10ns cycle time, 100MHz operation in Pipelined output mode
- Separate upper-byte and lower-byte controls for multiplexed bus and bus matching compatibility
- LVTTL- compatible, single 3.3V (±0.3V) power supply
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Available in a 128-pin Thin Quad Flatpack (TQFP) package
- Green parts available, see ordering information

Functional Block Diagram



NOTE:

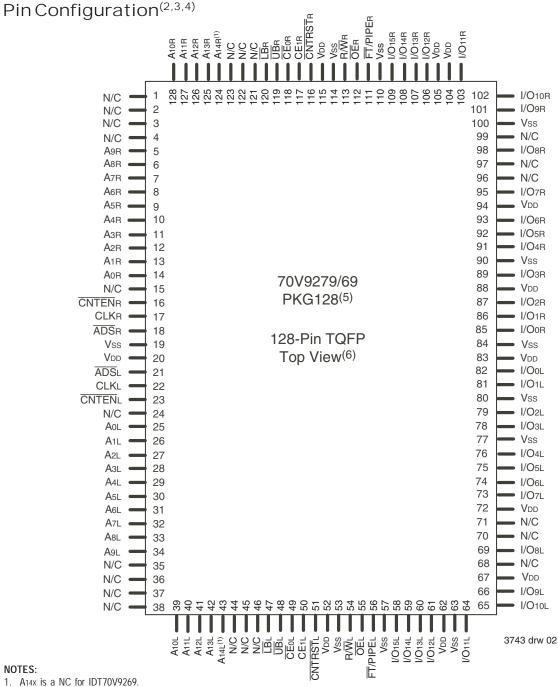
1. A₁₄x is a NC for IDT70V9269.

AUGUST 2019

Description:

The IDT70V9279/69 is a high-speed 32/16K x 16 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times.

With an input data register, the IDT70V9279/69 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by \overline{CE}_0 and CE₁, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using CMOS high-performance technology, these devices typically operate on only 429mW of power.



- 1. A14x is a NC for IDT70V9269.
- 2. All V_{DD} pins must be connected to power supply.
- 3. All Vss pins must be connected to ground.
- Package body is approximately 14mm x 20mm x 1.4mm.
- This package code is used to reference the package diagram.
- This text does not indicate orientation of the actual part-marking.



Pin Names

Left Port	Right Port	Names		
CEOL, CE1L	CEOR, CE1R	Chip Enables ⁽³⁾		
R/WL	R/WR	Read/Write Enable		
ŌĒL	OE R	Output Enable		
A0L - A14L ⁽¹⁾	A0R - A14R ⁽¹⁾	Address		
I/O0L - I/O15L	I/O0R - I/O15R	Data Input/Output		
CLKL	CLKR	Clock		
ŪB∟	UB R	Upper Byte Select ⁽²⁾		
<u>LB</u> L	<u>T</u> BR	Lower Byte Select ⁽²⁾		
ĀDSL	ADS R	Address Strobe Enable		
CNTENL	<u>CNTEN</u> R	Counter Enable		
CNTRSTL	<u>CNTRST</u> R	Counter Reset		
FT/PIPEL	FT/PIPER	Flow-Through / Pipeline		
V	DD	Power (3.3V)		
V	SS	Ground (0V)		

3743 tbl 01

NOTES:

- 1. Address A_{14x} is a NC for IDT70V9269.
- 2. \overline{LB} and \overline{UB} are single buffered regardless of state of $\overline{FT}/PIPE$.
- 3. $\overline{\text{CE}}_0$ and CE1 are single buffered when $\overline{\text{FT}}/\text{PIPE} = V_{\text{IL}}$, CEo and CE1 are double buffered when FT/PIPE = VIH, i.e. the signals take two cycles to deselect.

Truth Table I—Read/Write and Enable Control^(1,2,3)

ŌĒ	CLK	<u>C</u> E₀ ⁽⁵⁾	CE1 ⁽⁵⁾	UB ⁽⁴⁾	LB ⁽⁴⁾	R/W	Upper Byte I/O&15	Lower Byte I/O ₀₋₇	MODE
Х	1	Н	Х	Χ	Χ	Χ	High-Z	High-Z	Deselected-Power Down
Х	1	Х	L	Χ	Χ	Χ	High-Z	High-Z	Deselected-Power Down
Х	1	L	Н	Н	Н	Х	High-Z	High-Z	Both Bytes Deselected
Х	1	L	Н	L	Н	L	Din	High-Z	Write to Upper Byte Only
Х	1	L	Η	Н	L	L	High-Z	DATAIN	Write to Lower Byte Only
Х	1	Ш	Ι	L	L	L	DATAIN	DATAIN	Write to Both Bytes
L	1	L	Н	L	Н	Н	DATAout	High-Z	Read Upper Byte Only
L	1	L	Н	Н	L	Н	High-Z	DATAout	Read Lower Byte Only
L	1	L	Н	L	L	Н	DATAout	DATAout	Read Both Bytes
Н	1	L	Н	L	L	Х	High-Z	High-Z	Outputs Disabled

3743 tbl 02 NOTES:

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care.
- 2. ADS, CNTEN, CNTRST = X.
- 3. $\overline{\mathsf{OE}}$ is an asynchronous input signal.
- 4 LB and UB are single buffered regardless of state of FT/PIPE.

 5. CEo and CE1 are single buffered when FT/PIPE = VIL. CEo and CE1 are double buffered when FT/PIPE = VIL, i.e. the signals take two cycles to deselect.

Truth Table II—Address Counter Control (1,2,3)

11011	IUDIC	11 / ()	a ai o	<u> </u>	Odific	<u> </u>	11101	
External Address	Previous Internal Address	Internal Address Used	CLK	ĀDS	CNTEN	CNTRST	I/O ⁽³⁾	MODE
An	Х	An	1	L ⁽⁴⁾	Χ	Н	Dvo (n)	External Address Used
Х	An	An + 1	1	Н	L ⁽⁵⁾	Н	Dvo(n+1)	Counter Enabled—Internal Address generation
Х	An + 1	An + 1	1	Н	Н	Н	Dvo(n+1)	External Address Blocked—Counter disabled (An + 1 reused)
Х	Х	A0	1	Χ	Х	L ⁽⁴⁾	Dvo(0)	Counter Reset to Address 0

NOTES: 3743 tbl 03

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care.
- 2. \overline{CE}_0 , \overline{LB} , \overline{UB} , and \overline{OE} = VIL; CE1 and R/ \overline{W} = VIH.
- 3. Outputs configured in Flow-Through Output mode; if outputs are in Pipelined mode the data out will be delayed by one cycle.
- 4. ADS and CNTRST are independent of all other signals including CEo, CE1, UB and LB.
- 5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CE₀, CE₁, UB and LB.

Recommended Operating Temperature and Supply Voltage^(1,2)

Grade	Ambient Temperature	GND	V _{DD}
Commercial	0°C to +70°C	0V	3.3V <u>+</u> 0.3V
Industrial	-40°C to +85°C	0V	3.3V <u>+</u> 0.3V

NOTES: 3743 tbl 04

- Industrial temperature: for specific speeds, packages and powers contact your sales office.
- 2. This is the parameter Ta. This is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
VDD	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
V⊪	Input High Voltage	2.2	_	V _{DD} +0.3V ⁽²⁾	V
VIL	Input Low Voltage	-0.3 ⁽¹⁾	_	0.8	V

3743 tbl 05

NOTES:

- 1. $VIL \ge -1.5V$ for pulse width less than 10 ns.
- 2. VTERM must not exceed VDD + 0.3V.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
TBIAS ⁽³⁾	Temperature Under Bias	-55 to +125	٥C
Tstg	StorageTemperature	-65 to +150	۰C
NLT	Junction Temperature	+150	۰C
Іоит	DC Output Current	50	mA

3743 tbl 06

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may
 cause permanent damage to the device. This is a stress rating only and functional
 operation of the device at these or any other conditions above those indicated
 in the operational sections of this specification is not implied. Exposure to absolute
 maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed Vpb + 0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq Vpb + 0.3V.
- 3. Ambient Temperature Under DC Bias. No AC Conditions. Chip Deselected.

Capacitance⁽¹⁾

 $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter	Conditions	Max.	Unit
Cin	Input Capacitance	VIN = 0V	9	pF
Соит ⁽²⁾	Output Capacitance	Vout = 0V	10	pF

NOTES

3743 tbl 07

- These parameters are determined by device characterization, but are not production tested.
- 2. Cout also references CI/O.

DC Electrical Characteristics Over the Operating

Temperature and Supply Voltage Range (VDD = 3.3V ± 0.3V)

			70V92	79/69S	70V92	79/69L	
Symbol	Parameter	Test Conditions	Min.	Max.	Min.	Max.	Unit
Iu	Input Leakage Current ⁽¹⁾	$V_{DD} = 3.6V$, $V_{IN} = 0V$ to V_{DD}	_	10	_	5	μΑ
ILO	Output Leakage Current	CEO = VIH or CE1 = VIL, VOUT = 0V to VDD	_	10	_	5	μΑ
Vol	Output Low Voltage	IOL = +4mA	_	0.4	_	0.4	V
Vон	Output High Voltage	Iон = -4mA	2.4	_	2.4	_	V

NOTE:

1. At $V_{DD} \le 2.0V$ input leakages are undefined.

3743 tbl 08

3743 tbl 09a

DC Electrical Characteristics Over the Operating

Temperature Supply Voltage Range (3,6) (Vpp = 3,3V ± 0,3V)

		ppry vortage R						0 = 3.3V 79/69X6 I Only	70V927 Co	79/69X7 m'l Ind		79/69X9 Only	
Symbol	Parameter	Test Condition	Versio	n	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Unit		
ldd	Dynamic Operating Current (Both			S L	220 220	395 350	200 200	335 290	180 180	260 225	mA		
	Ports Active)	$f = f_{MAX}^{(1)}$	IND	S L		_	200 200	370 335	_				
ISB1	Standby Current (Both Ports - TTL	$\overline{CE}L = \overline{CE}R = VIH$ $f = fMAX^{(1)}$	COM'L	S L	70 70	145 130	60 60	115 100	50 50	75 65	mA		
	Level Inputs)		IND	S L		_	60 60	130 115	_	_			
ISB2	Standby Current (One Port - TTI One CE"-B" = VIL and CE"-B" = VIH One	COM'L	S L	150 150	280 250	130 130	240 210	110 110	170 150	mA			
	Level Inputs)	Active Port Outputs Disabled, f=fMAX ⁽¹⁾	IND	S L			130 130	265 240					
ISB3	Full Standby Current (Both	Both Ports $\overline{CE}L$ and $\overline{CE}R \ge VDD - 0.2V$,	COM'L	S L	1.0 0.4	5 3	1.0 0.4	5 3	1.0 0.4	5 3	mA		
	Ports - CMOS Level Inputs) VIN ≥	$VIN \ge VDD - 0.2V \text{ or } VIN \le 0.2V, f = 0^{(2)}$	IND	S L			1.0 0.4	20 15					
ISB4	Current (One $\overline{CE}^*B^* \ge V_{DD} - 0.2V^{(5)}$	COM'L	S L	140 140	270 240	120 120	230 200	100 100	160 140	mA			
	Level Inputs)	$\begin{array}{l} \text{VIN} \geq \text{VDD} - 0.2 \text{V or} \\ \text{VIN} \leq 0.2 \text{V, Active Port,} \\ \text{Outputs Disabled, } f = \text{fMax}^{(1)} \end{array}$	IND	S L			120 120	255 230					

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of Vss to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. $V_{DD} = 3.3V$, $T_{A} = 25^{\circ}C$ for Typ, and are not production tested. I_{DD} DC(f=0) = 90mA (Typ). 5. $\overline{CE}_{X} = V_{IL}$ means $\overline{CE}_{DX} = V_{IL}$ and $CE_{1X} = V_{IH}$
- - $\overline{CE}x = V_{IH} \text{ means } \overline{CE}_{0X} = V_{IH} \text{ or } CE_{1X} = V_{IL}$
 - $\overline{\text{CE}}\text{x} \leq 0.2 \text{V}$ means $\overline{\text{CE}}\text{ox} \leq 0.2 \text{V}$ and $\text{CE}\text{1x} \geq \text{V}_{\text{DD}}$ 0.2 V
 - $\overline{\text{CE}}$ x \geq Vdd 0.2V means $\overline{\text{CE}}$ 0x \geq Vdd 0.2V or CE1x \leq 0.2V
 - 'X' represents "L" for left port or "R" for right port.
- 6. 'X' in part numbers indicate power rating (S or L).

3743 tbl 09b



70V9279/69S/L High-Speed 32/16K x 16 Dual-Port Synchronous Static RAM

DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range^(3,6) (VDD = $3.3V \pm 0.3V$)(Cont'd)

·		i voitage			70V927	9/69X12 I Only		9/69X15 I Only	
Symbol	Parameter	Test Condition	Versio	n	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Unit
IDD	Dynamic Operating	CEL and CER= VIL, Outputs Disabled, f = fMAX ⁽¹⁾	COM'L	S L	150 150	240 205	130 130	220 185	mA
	Current (Both Ports Active)		IND	S L					
ISB1	Standby Current (Both Ports - TTL	$\overline{CE}L = \overline{CE}R = VIH$ $f = fMAX^{(1)}$	COM'L	S L	40 40	65 50	30 30	55 35	mA
	Level Inputs)		IND	S L					
ISB2	Standby Current (One	urrent (One $\overline{CE}^*B^* = VIH^{(S)}$ Active Port Outputs Disabled,	COM'L	S L	100 100	160 140	90 90	150 130	mA
	Level Inputs)		IND	S L					
ISB3	Full Standby Current (Both	Both Ports CEL and CER > VDD - 0.2V,	COM'L	S L	1.0 0.4	5 3	1.0 0.4	5 3	mA
	Ports - CMOS Level Inputs)	$VIN \ge VDD - 0.2V \text{ or } VIN \le 0.2V, f = 0^{(2)}$	IND	S L					
ISB4	Full Standby Current (One Port - CMOS	\overline{CE} "A" $\leq 0.2V$ and \overline{CE} "B" $\geq V$ DD $-0.2V$ ⁽⁵⁾	COM'L	S L	90 90	150 130	80 80	140 120	mA
	Level Inputs)	$VIN \ge \overline{V}_{DD}$ - 0.2V or $VIN \le 0.2V$, Active Port, Outputs Disabled, $f = fMax^{(1)}$	IND	S L					

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of Vss to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. $V_{DD} = 3.3V$, $T_{A} = 25^{\circ}C$ for Typ, and are not production tested. $I_{DD} \ DC(f=0) = 90 \text{mA}$ (Typ). 5. $\overline{CE}x = V_{IL} \ means \overline{CE}_{DX} = V_{IL} \ and \ CE_{IX} = V_{IH}$
- - $\overline{\text{CE}}\text{x} = \text{Vih means } \overline{\text{CE}}\text{ox} = \text{Vih or CE}\text{1x} = \text{Vil}$

 - 'X' represents "L" for left port or "R" for right port.
- 6. 'X' in part numbers indicate power rating (S or L).



AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1, 2, and 3

7343 tbl 10

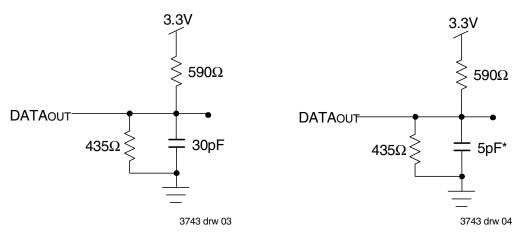


Figure 1. AC Output Test load.

Figure 2. Output Test Load (For tcklz, tckHz, tolz, and toHz). *Including scope and jig.

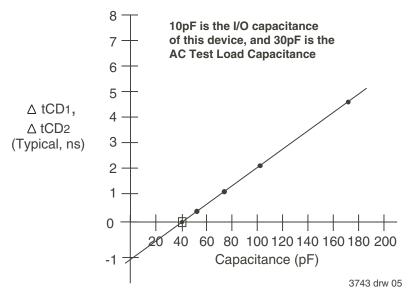


Figure 3. Typical Output Derating (Lumped Capacitive Load).



AC Electrical Characteristics Over the Operating Temperature Range

(Read and Write Cycle Timing) $^{(3,4)}$ (VDD = 3.3V ± 0.3V, TA = 0°C to +70°C)

		70V92 Com	79/69X6 'I Only	Co	79/69X7 om'l Ind	70V9279/69X9 Com'l Only		
Symbol	Parameter	Min.	Мах.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	19	_	22	_	25	_	ns
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	10	_	12	_	15	_	ns
tcн1	Clock High Time (Flow-Through) ⁽²⁾	6.5	_	7.5	_	12	_	ns
tcl1	Clock Low Time (Flow-Through) ⁽²⁾	6.5	_	7.5	_	12	_	ns
tcH2	Clock High Time (Pipelined) ⁽²⁾	4	_	5	_	6	_	ns
tcl2	Clock Low Time (Pipelined) ⁽²⁾	4	_	5	_	6	_	ns
tr	Clock Rise Time	_	3	_	3	_	3	ns
tF	Clock Fall Time	_	3	_	3	_	3	ns
tsa	Address Setup Time	3.5	_	4	_	4	_	ns
tha	Address Hold Time	0	_	0	_	1	_	ns
tsc	Chip Enable Setup Time	3.5	_	4	_	4	_	ns
tнc	Chip Enable Hold Time	0	_	0	_	1	_	ns
tsw	R/W Setup Time	3.5	_	4	_	4	_	ns
tHW	R/W Hold Time	0	_	0	_	1	_	ns
tsd	Input Data Setup Time	3.5	_	4	_	4	_	ns
thd	Input Data Hold Time	0	_	0	_	1	_	ns
tsad	ADS Setup Time	3.5	_	4	_	4	_	ns
thad	ADS Hold Time	0	_	0	_	1	_	ns
tscn	CNTEN Setup Time	3.5	_	4	_	4	_	ns
thcn	CNTEN Hold Time	0	_	0	_	1	_	ns
tsrst	CNTRST Setup Time	3.5		4	_	4	_	ns
thrst	CNTRST Hold Time	0	_	0	_	1	_	ns
toe	Output Enable to Data Valid		6.5	_	7.5	_	9	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2	_	2	_	2	_	ns
tонz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	1	7	ns
tcd1	Clock to Data Valid (Flow-Through) ⁽²⁾		15	_	18	_	20	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾		6.5	_	7.5	_	9	ns
toc	Data Output Hold After Clock High	2	_	2	_	2	_	ns
tckhz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	2	9	ns
tcklz	Clock High to Output Low-Z ⁽¹⁾	2	_	2	_	2	_	ns
Port-to-Port D		<u> </u>					•	
tcwdd	Write Port Clock High to Read Data Delay	_	24	_	28	_	35	ns
tccs	Clock-to-Clock Setup Time	_	9	_	10	_	15	ns

NOTES: 3743 tol 17:

^{1.} Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

^{2.} The Pipelined output parameters (tcvc2, tcb2) apply to either or both left and right ports when FT/PIPE = VIH. Flow-through parameters (tcvc1, tcb1) apply when FT/PIPE = VIL for that port.

^{3.} All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

^{4. &#}x27;X' in part number indicates power rating (S or L).



AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing) $^{(3,4)}$ (VDD = 3.3V ± 0.3V, TA = 0°C to +70°C)(Cont'd)

	Parameter		70V9279/69X12 Com'l Only		70V9279/69X15 Com'l Only		
Symbol			Max.	Min.	Max.	Unit	
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	30	_	35	_	ns	
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	20	_	25	_	ns	
tcH1	Clock High Time (Flow-Through) ⁽²⁾	12	_	12	— n		
tCL1	Clock Low Time (Flow-Through) ⁽²⁾	12	_	12	_	ns	
tCH2	Clock High Time (Pipelined) ⁽²⁾	8	_	10	_	ns	
tCL2	Clock Low Time (Pipelined) ⁽²⁾	8	_	10	_	ns	
tr	Clock Rise Time		3	_	3	ns	
tF	Clock Fall Time	_	3	_	3	ns	
tsa	Address Setup Time	4	_	4	_	ns	
tha	Address Hold Time	1	_	1	_	ns	
tsc	Chip Enable Setup Time	4	_	4	_	ns	
thc	Chip Enable Hold Time	1	_	1	_	ns	
tsw	R/W Setup Time	4	_	4	_	ns	
thw	R/W Hold Time	1	_	1 —		ns	
tsd	Input Data Setup Time	4	_	4	_	ns	
thD	Input Data Hold Time	1	_	1 —		ns	
tsad	ADS Setup Time	4	_	- 4 —		ns	
thad	ADS Hold Time	1 — 1			ns		
tscn	CNTEN Setup Time	4		4		ns	
thcn	CNTEN Hold Time	1	_	1	_	ns	
tsrst	CNTRST Setup Time	4		4		ns	
thrst	CNTRST Hold Time	1	_	1	_	ns	
toe	Output Enable to Data Valid		12	_	15	ns	
tolz	Output Enable to Output Low-Z ⁽¹⁾	2	_	2	_	ns	
toнz	Output Enable to Output High-Z ⁽¹⁾	1	7	7 1 7		ns	
tcD1	Clock to Data Valid (Flow-Through) ⁽²⁾		25	5 — 30		ns	
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾		12	<u> </u>		ns	
toc	Data Output Hold After Clock High	2	_	2	2 —		
tckhz	Clock High to Output High-Z ⁽¹⁾	2	9	2	ns		
tcklz	Clock High to Output Low-Z ⁽¹⁾ 2 — 2 —					ns	
Port-to-Port [Delay						
tcwdd	Write Port Clock High to Read Data Delay		40	_	50	ns	
tccs	Clock-to-Clock Setup Time		15	_	20	ns	

^{1.} Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

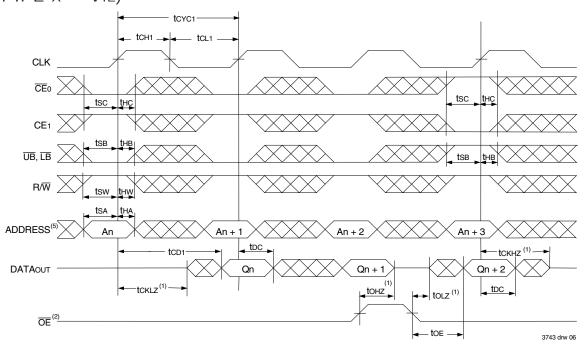
^{2.} The Pipelined output parameters (tcvc2, tcb2) apply to either or both left and right ports when FT/PIPE = ViH. Flow-through parameters (tcvc1, tcb1) apply when FT/PIPE = ViL for that port.

^{3.} All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

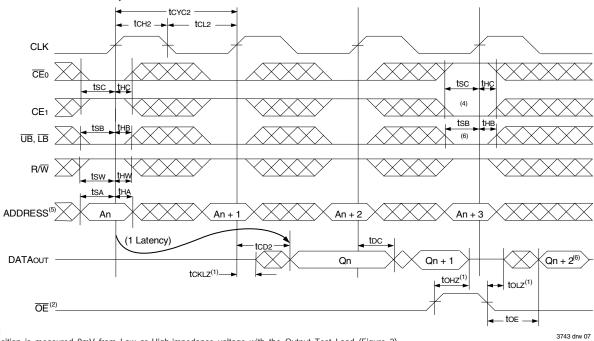
^{4. &#}x27;X' in part number indicates power rating (S or L).



Timing Waveform of Read Cycle for Flow-through Output $(\mathbf{FT}/PIPE"x" = VIL)^{(3,7)}$



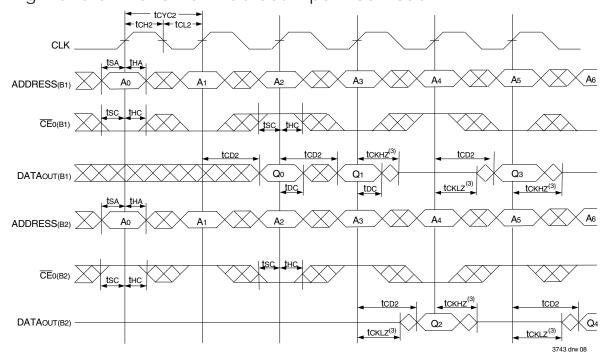
Timing Waveform of Read Cycle for Pipelined Output $(\mathbf{FT}/PIPE"x" = VIH)^{(3,7)}$



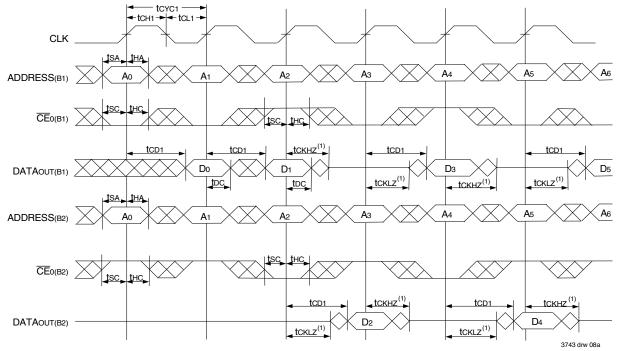
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. $\overline{\text{OE}}$ is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. $\overline{ADS} = VIL$, \overline{CNTEN} and $\overline{CNTRST} = VIH$.
- 4. The output is disabled (High-Impedance state) by $\overline{\text{CE}}_0 = \text{V}_{\text{IH}}$ or CE1 = V_{IL} following the next rising edge of the clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 6. If $\overline{\sf UB}$ or $\overline{\sf LB}$ was HIGH, then the Upper Byte and/or Lower Byte of DATAouT for Qn + 2 would be disabled (High-Impedance state).
- 7. "x" denotes Left or Right port. The diagram is with respect to that port.



Timing Waveform of a Bank Select Pipelined Read (1,2)



Timing Waveform of a Bank Select Flow-Through Read⁽⁶⁾

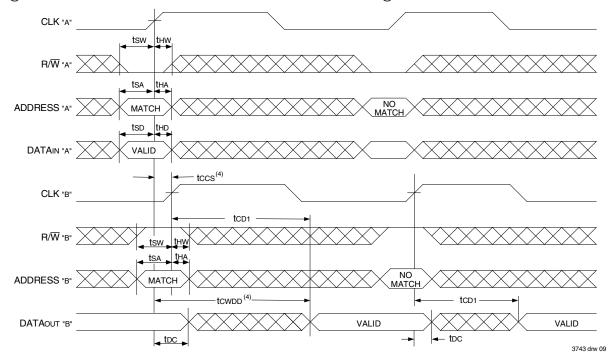


- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V9279/69 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{UB} , \overline{LB} , \overline{OE} , and \overline{ADS} = VIL; CE1(B1), CE1(B2), R/ \overline{W} , \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. \overline{CE}_0 , \overline{UB} , \overline{LB} , and \overline{ADS} = VIL; CE1, \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 5. \overline{OE} = V_{IL} for the Right Port, which is being read from. \overline{OE} = V_{IH} for the Left Port, which is being written to.
- 6. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpd.

 If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpd does not apply in this case.



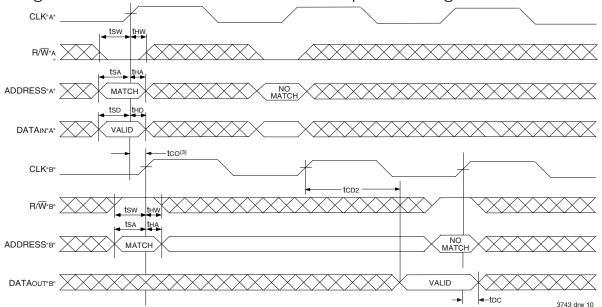
Timing Waveform with Port-to-Port Flow-Through Read (1,2,3,5)



NOTES

- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. \overline{CE}_0 , \overline{UB} , \overline{LB} , and $\overline{ADS} = VIL$; \overline{CE}_1 , \overline{CNTEN} , and $\overline{CNTRST} = VIH$.
- 3. \overline{OE} = VIL for the Right Port, which is being read from. \overline{OE} = VIH for the Left Port, which is being written to.
- 4. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpb.
 If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpb does not apply in this case.
- 5. All timing is the same for both left and right ports. Port "A" may be either left or right port. Port "B" is the opposite of Port "A".

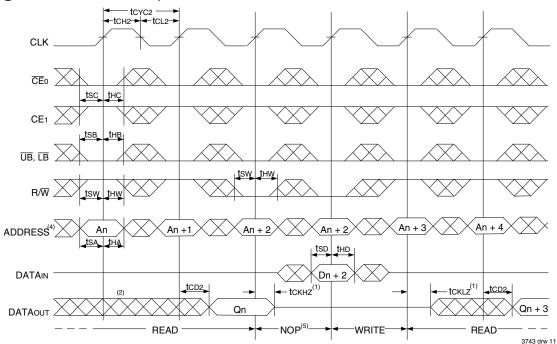
Timing Waveform of Left Port Write to Pipelined Right Port Read (1,2,4)



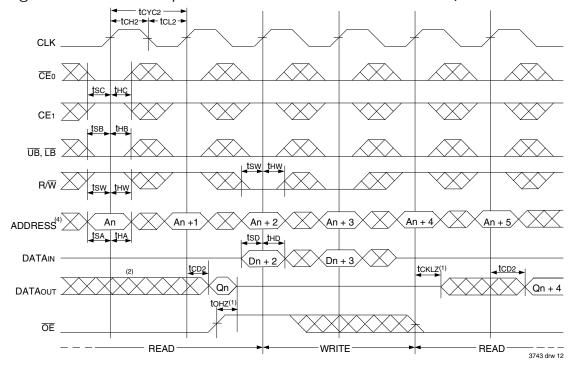
- 1. $\overline{CE_0}$, $\overline{BE_n}$, and $\overline{ADS} = VIL$; CE_1 , \overline{CNTEN} , and $\overline{REPEAT} = VIH$.
- 2. $\overline{OE} = V_{IL}$ for Port "B", which is being read from. $\overline{OE} = V_{IH}$ for Port "A", which is being written to.
- 3. If tco ≤ minimum specified, then data from Port "B" read is not valid until following Port "B" clock cycle (ie, time from write to valid read on opposite port will be tco + 2 tcyc2 + tco2). If tco > minimum, then data from Port "B" read is available on first Port "B" clock cycle (ie, time from write to valid read on opposite port will be tco + tcyc2 + tco2).
- 4. All timing is the same for Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite of Port "A"



Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** = VIL)(3)



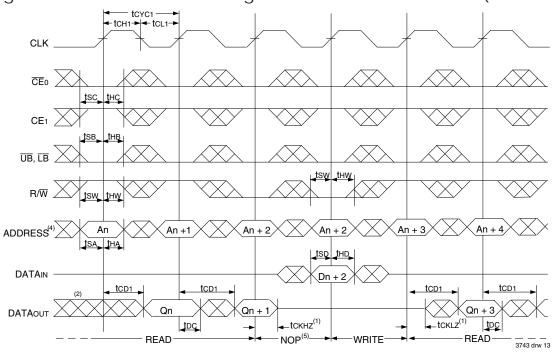
Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** Controlled)(3)



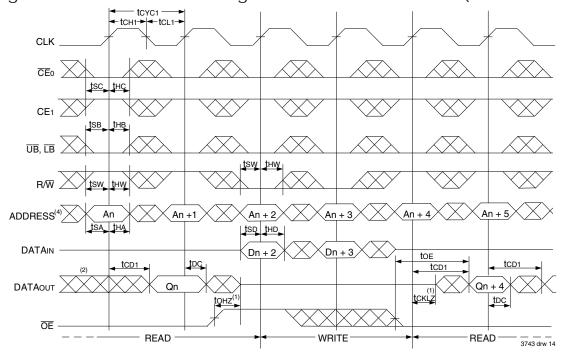
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. $\overline{\text{CE}}_0$, $\overline{\text{UB}}$, $\overline{\text{LB}}$, and $\overline{\text{ADS}} = \text{VIL}$; $\overline{\text{CE}}_1$, $\overline{\text{CNTEN}}$, and $\overline{\text{CNTRST}} = \text{VIH}$.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.



Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** = VIL)(3)



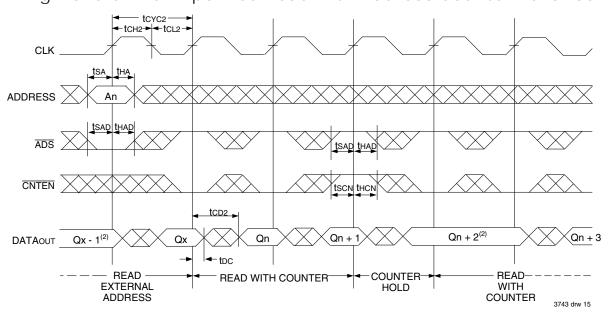
Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)⁽³⁾



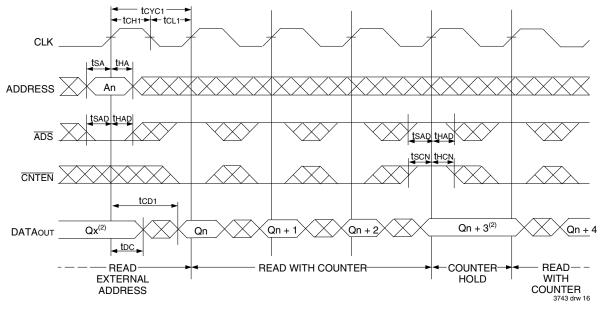
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. \overline{CE}_0 , \overline{UB} , \overline{LB} , and \overline{ADS} = VIL; \overline{CE}_1 , \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.



Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾



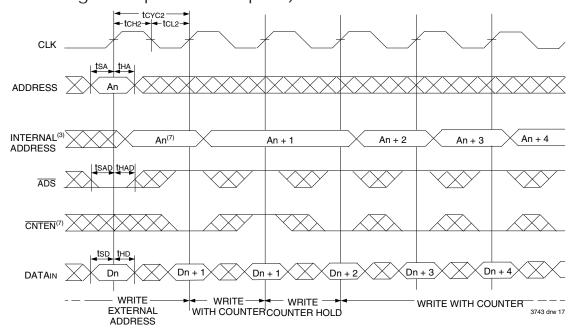
Timing Waveform of Flow-Through Read with Address Counter Advance⁽¹⁾



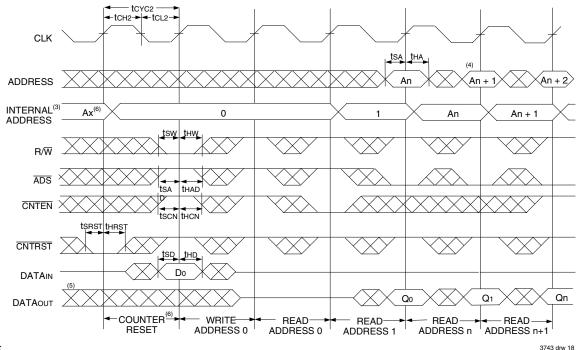
- 1. \overline{CE}_0 , \overline{OE} , \overline{UB} , and \overline{LB} = VIL; CE1, R/ \overline{W} , and \overline{CNTRST} = VIH.
- 2. If there is no address change via $\overline{ADS} = VIL$ (loading a new address) or $\overline{CNTEN} = VIL$ (advancing the address), i.e. $\overline{ADS} = VIH$ and $\overline{CNTEN} = VIH$, then the data output remains constant for subsequent clocks.



Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾



Timing Waveform of Counter Reset (Pipelined Outputs)(2)



- 1. $\overline{CE_0}$, \overline{UB} , \overline{LB} , and $R/\overline{W} = V_{IL}$; CE_1 and $\overline{CNTRST} = V_{IH}$.
- 2. \overline{CE}_0 , \overline{UB} , \overline{LB} = VIL; CE1 = VIH.
- 3. The "Internal Address" is equal to the "External Address" when ADS = V_{IL} and equals the counter output when ADS = V_{IL}
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. ADDRo will be accessed. Extra cycles are shown here simply for clarification.
- 7. CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance.
 The 'An +1'Address is written to during this cycle.

Functional Description

The IDT70V9279/69 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

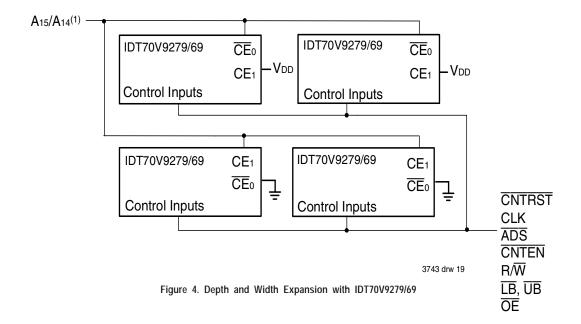
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to staff the operation of the address counters for fast interleaved memory applications.

A HIGH on $\overline{\text{CE}}$ o or a LOW on CE1 for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9279/69's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with $\overline{\text{CE}}$ 0 LOW and CE1 HIGH to reactivate the outputs.

Depth and Width Expansion

The IDT70V9279/69 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

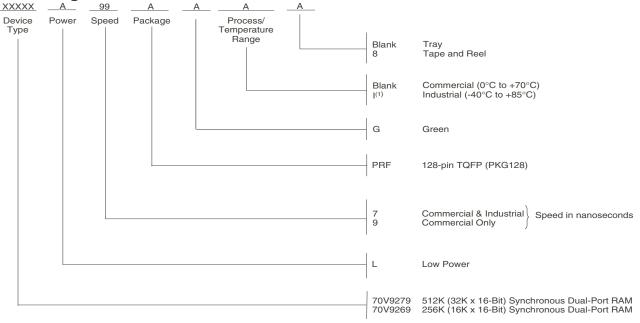
The IDT70V9279/69 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 32-bit or wider applications.



NOTE:

1. A15 is for IDT70V9279. A14 is for IDT70V9269.





NOTES: 3743 drw 20

Contact your local sales office for industrial temp. range for other speeds, packages and powers.
 LEAD FINISH (SnPb) parts are Obsolete. Product Discontinuation Notice - PDN# SP-17-02
 Note that information regarding recently obsoleted parts are included in this datasheet for customer convenience.

Ordering Information for Flow-through Devices

Old Flow-through Part	New Combined Part
70V927S/L25	70V9279L7
70V927S/L30	70V9279L9

3743 tbl 12

IDT Clock Solution for IDT70V9279/69 Dual-Port

IDT Dual-Port Part Number	Dual-Port I/O Specitications		Clock Specifications				IDT	IDT
	Voltage	I/O	Input Capacitance	Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	PLL Clock Device	Non-PLL Clock Device
70V9279/69	3.3	LVTTL	9pF	40%	100	150ps	2305 2308 2309	49FCT3805 49FCT3805D/E 74FCT3807 74FCT3807D/E

3743 tbl 13

Orderable Part Information

<u> </u>					
Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade	
7	70V9279L7PRFG	PKG128	TQFP	С	
	70V9279L7PRFG8	PKG128	TQFP	С	
	70V9279L7PRFGI PKG128 TQFP		I		
	70V9279L7PRFGI8	PKG128	TQFP	Ī	

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
9	70V9269L9PRFG	PKG128	TQFP	С
	70V9269L9PRFG8	PKG128	TQFP	С



Industrial and Commercial Temperature Ranges

Datasheet Document History

01/12/99:		Initiated datasheet document history
		Converted to new format
		Cosmetic and typographical corrections
	Dogo 14	Added additional notes to pin configurations
04/15/00.	Page 14	Added Depth & Width Expansion section
06/15/99:	Page 4	Deleted note 6 for Table II
09/29/99:	Page 7	Corrected typo in heading
11/10/99:		Replaced IDT logo
03/31/00:		Combined Pipelined 70V9279/69 family and Flow-through 70V927 family offerings into one data sheet Changed ±200mV in waveform notes to 0mV
		Added corresponding part chart with ordering information
01/017/01:	Page 4	Changed information in Truth Table II
		Increased storage temperature parameters
		Clarified TA parameter
	Page 5	DC Electrical parameters-changed wording from "open" to "disabled"
		Removed Preliminary status
02/25/04:		Consolidated multiple devices into one datasheet
		Changed naming conventions from Vcc to Vdd and from GND to Vss
	Page 2	Added date revision for pin configuration
	Page 3	Added footnotes for $\overline{\sf UB}$, $\overline{\sf LB}$, $\overline{\sf CE}$ 0 and CE1 buffer conditions when $\overline{\sf FT}$ or PIPE
	Page 4	Added junction temperature to Absolute Maximum Ratings Table
		Added Ambient Temperature footnote
	Page 5	Added I-temp numbers for 9ns speed to DC Electrical Characteristics Table
		Added 6ns speed DC power numbers to the DC Electrical Characteristics Table
	Page 7	Added I-temp for 9ns speed to AC Electrical Characteristics Table
		Added 6ns speed AC timing numbers to the AC Electrical Characteristics Table
	Page 18	Added 6ns speed grade and 9ns I-temp to ordering information
	D 10.10	Added IDT Clock Solution Table
05/04/04	Page 1 & 19	Updated IDT logo, replaced IDT™ logo with IDT® logo
05/04/04:	Page 1 & 18	Added 7ns speed grade to ordering information
	Page 5	Added 7ns speed DC power numbers to the DC Electrical Characteristics Table
10/11/04	Page 8	Added 7ns speed AC timing numbers to the AC Electrical Characteristics Table
10/11/04:	Page 4	Updated Capacitance table Added Tas I tomp and removed Ons I tomp DC never numbers from the DC Electrical Characteristics table
	Page 5	Added 7ns I-temp and removed 9ns I-temp DC power numbers from the DC Electrical Characteristics table Added 7ns I-temp and removed 9ns I-temp from the AC Electrical Characteristics table
	Page 8 Page 12	Added 7 is receipt and removed 3 is receipt of the Act Electrical Characteristics table. Added Timing Waveform of Left Port Write to Pipelined Right Port Read
	Page 18	Added Timing Wavelott for Write to Fipelined Right Fort Read Added 7ns I-temp and removed 9ns I-temp from ordering information
01/19/06:	Page 1	Added yns i temp and removed yns remphornordening information Added green availability to features
01/17/00.	Page 18	Added green indicator to ordering information
10/23/08:	Page 18	Removed "IDT" from orderable part number
06/25/18:	1 age 10	Added Tape & Reel to Ordering Information
00/25/10.		Product Discontinuation Notice - PDN# SP-17-02
		Last time buy expires June 15, 2018
08/06/19:	Page 1 & 18	Deleted obsolete Commercial speed grades 6/12/15ns
	Page 2	Updated package code PK-128 to PKG128
	Page 18	Added Orderable Part Information table

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